

## ABSTRACT

A method and apparatus for reducing the contaminants in a wet etching bath by rapidly removing a substantial portion of the etching liquid from the bath such that the contaminants are removed from the air/liquid interface of the bath surface is described. By rapidly removing a substantial portion of the etching liquid from the bath, contaminants that are trapped by eddy currents and liquid/air surface tension forces are greatly reduced at the surface of the bath. The semiconductor wafers treated showed reduced levels of contamination.

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